Abstract

Apparatus for etching a semiconductor wafer

The invention relates to an apparatus for etching a semiconductor wafer similar to an etching cell, having a basic body, on the upper side of which the semiconductor wafer can be attached with its one side, sealed from the outside in the edge region by means of a peripheral seal.

In order to be able to manufacture such an apparatus with as little expenditure as possible, according to the invention the seal comprises two spaced-apart, peripheral sealing lips (2, 3), and a negative-pressure line (4) opens out in the region between the sealing lips (2, 3).

FIGURE 1